

Abstract:

The invention concerns a film (66) having at least one electrical component and a process for the production of such a film. An adhesive layer comprising a radiation-cross-linkable adhesive is applied to a base film (61). The adhesive layer is applied to the base film in a form of being structured in pattern form and/or is irradiated in pattern form in such a way that the adhesive layer hardens with structuring in pattern form. A transfer film (41) which comprises a carrier film and an electrical functional layer is applied to the adhesive layer. The carrier film (41) is pulled off the film body comprising the base film, the adhesive layer and the electrical functional layer, wherein in a first region structured in pattern form the electrical functional layer remains on the base film (61) and in a second region structured in pattern form the electrical functional layer remains on the carrier film and is pulled off the base film (61) with the carrier film.

(Figure 2)